

conga-TFS

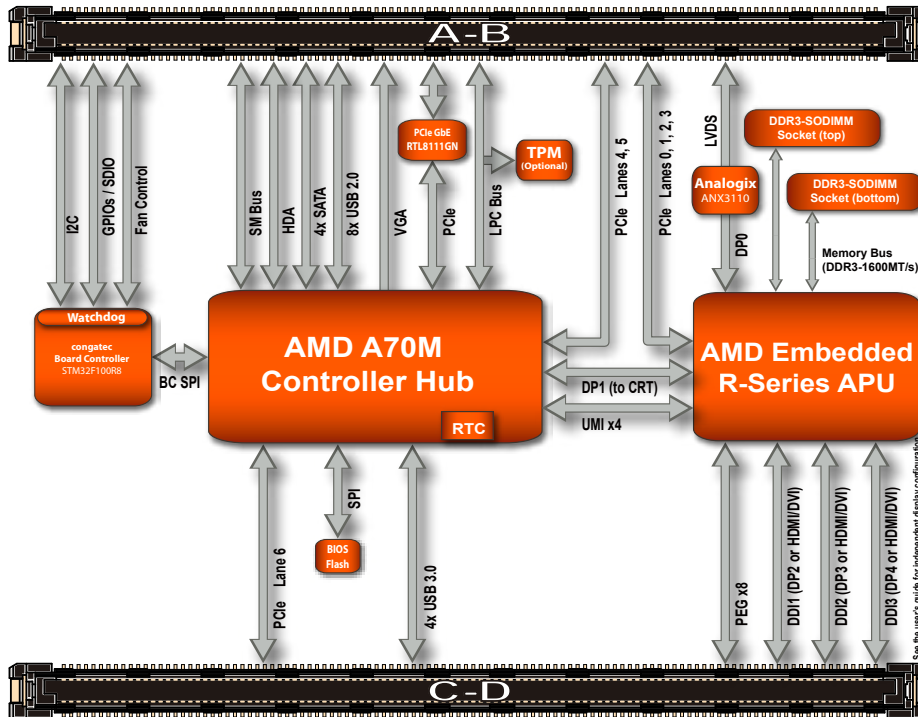


- Power efficient high-performance x86 processing
- Unprecedented integrated graphics performance
- High performance parallel processing support

COM  **Express**[®]

| | | | | | | |
|---------------------------|---|-------------------------------|---------------|---------|----------|-----|
| Formfactor | COM Express™ Basic (95 x 125 mm) Type 6 Connector Layout | | | | | |
| CPU | AMD Embedded R-Series processors | | | | | |
| | AMD Embedded R-464L | AMD Radeon™ HD 7660G Graphics | Quad-Core 2.3 | 3.2 GHz | TDP 35 W | PGA |
| | AMD Embedded R-460H | AMD Radeon™ HD 7640G Graphics | Quad-Core 1.9 | 2.8 GHz | TDP 35 W | PGA |
| | AMD Embedded R-272F | AMD Radeon™ HD 7520G Graphics | Dual-Core 2.7 | 3.2 GHz | TDP 35 W | PGA |
| DRAM | Two 1.5V/1.35V DDR3 SO-DIMMs up to 1600MT/s and 8 GByte | | | | | |
| Chipset | AMD A70M Controller Hub | | | | | |
| Ethernet | Realtek RTL8111E GbE LAN Controller | | | | | |
| I/O Interfaces | 7x PCI Express™ 2.0 lane PCI Express™ 2.0 x8 link 4x SATA 6Gb/s with RAID 0/1 4x USB 3.0 8x USB 2.0 2x Express™Card LPC bus SDHC I²C bus | | | | | |
| Sound | High Definition Audio Interface | | | | | |
| Graphics | High performance DirectX®11 GPU supports OpenCL™ 1.1 and OpenGL 4.2 Three Independent Display Controllers Dedicated Hardware (UVD) for H.264 MPEG4 Part 2 VC-1 and MPEG2 decode Dedicated Hardware (VCE) assisted encoding of HD video streams to H.264 | | | | | |
| LVDS | 18/24-bit Single/Dual Channel Interface resolutions up to 1920x1200@60Hz VESA standard or JEIDA data mapping Automatic Panel Detection via EDID/EPI | | | | | |
| DisplayPort | Three DisplayPort 1.2 | | | | | |
| HDMI or DVI | Two Ports support one HDMI1.4a and two Single-Link DVI | | | | | |
| VGA | One Port supports resolutions up to 1920x1200@60Hz | | | | | |
| congatec Board Controller | Multi Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics BIOS Setup Data Backup I2C bus Power Loss Control | | | | | |
| Embedded BIOS Features | AMI Aptio® UEFI firmware | | | | | |
| Security | The conga-TFS can be optionally equipped with a discrete "Trusted Platform Module" (TPM). It is capable of calculating efficient hash and RSA algorithms with key lengths up to 2,048 bits and includes a real random number generator. Security sensitive applications such as gaming and e-commerce will benefit also with improved authentication integrity and confidence levels. | | | | | |
| Power Management | ACPI 3.0 with battery support | | | | | |
| Operating Systems | Microsoft® Windows 8 Microsoft® Windows 7 Linux Microsoft® Windows® embedded Standard | | | | | |
| Power Consumption | Typ. application: tbd. see manual for full details CMOS Battery Backup | | | | | |
| Temperature | Operating: 0 .. +60°C Storage: -20 .. +80°C | | | | | |
| Humidity | Operating: 10 - 90% r. H. non cond. Storage: 5 - 95% r. H. non cond. | | | | | |
| Size | 95 x 125 mm (3.74" x 4.92") | | | | | |

conga-TFS | Block diagram



conga-TFS | Order Information

| Article | PN | Description |
|-------------------------|--------|--|
| conga-TFS/R-464L | 041101 | AMD embedded R-Series R-464L quad core processor with 2.3GHz 2x2MB L2 cache and 1600MT/s DDR3 SODIMM memory interface for up to 16GB |
| conga-TFS/R-460H | 041102 | AMD embedded R-Series R-460H quad core processor with 1.9GHz 2x2MB L2 cache and 1600MT/s DDR3 SODIMM memory interface for up to 16GB |
| conga-TFS/R-272F | 041103 | AMD embedded R-Series R-272F dual core processor with 2.7GHz 1MB L2 cache and 1600MT/s DDR3 SODIMM memory interface for up to 16GB |
| conga-TFS/HSP-B | 041150 | Standard heatspreader for high performance COM Express module conga-TFS with integrated flat heat pipe. All standoffs are with 2.7mm bore hole |
| conga-TFS/HSP-T | 041151 | Standard heatspreader for high performance COM Express module conga-TFS with integrated flat heat pipe. All standoffs are M2.5mm thread |
| conga-TFS/CSA-B | 041154 | Standard active cooling solution for high performance COM Express module conga-TFS with integrated flat heat pipe 15mm fins 20mm overall heat sink height and integrated 12V fan. All standoffs are with 2.7mm bore hole |
| conga-TFS/CSA-T | 041155 | Standard active cooling solution for high performance COM Express module conga-TFS with integrated flat heat pipe 15mm fins 20mm overall heat sink height and integrated 12V fan. All standoffs are M2.5mm thread |
| DDR3L-SODIMM-1600 (2GB) | 068755 | DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 2GB RAM |
| DDR3L-SODIMM-1600 (4GB) | 068756 | DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 4GB RAM |
| DDR3L-SODIMM-1600 (8GB) | 068757 | DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 8GB RAM |

Accessories

| | | |
|------------------------------------|--------|---|
| conga-TEVAL | 065800 | Evaluation carrier board for Type 6 COM-Express-modules |
| conga-Cdebug | 047854 | COM-Express debugging platform Including cable for COM PS/2 and VGA. |
| conga-LDVI/EPI | 011115 | LVDS to DVI converter board for digital flat panels with onboard EEPROM |
| conga-HDMI/Display Port adapter | 500014 | The conga-HDMI/DisplayPort adapter is used fo convert the chipset graphic ports Port-B Port-C and Port-D to the HDMI or DisplayPort Interface |
| COM-Express-carrier-board-Socket-5 | 400007 | Connector for COM-Express carrier boards height 5mm packing unit 4 pieces |
| COM-Express-carrier-board-Socket-8 | 400004 | Connector for COM-Express carrier boards height 8mm packing unit 4 pieces |

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